



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: L-36BGD

Green

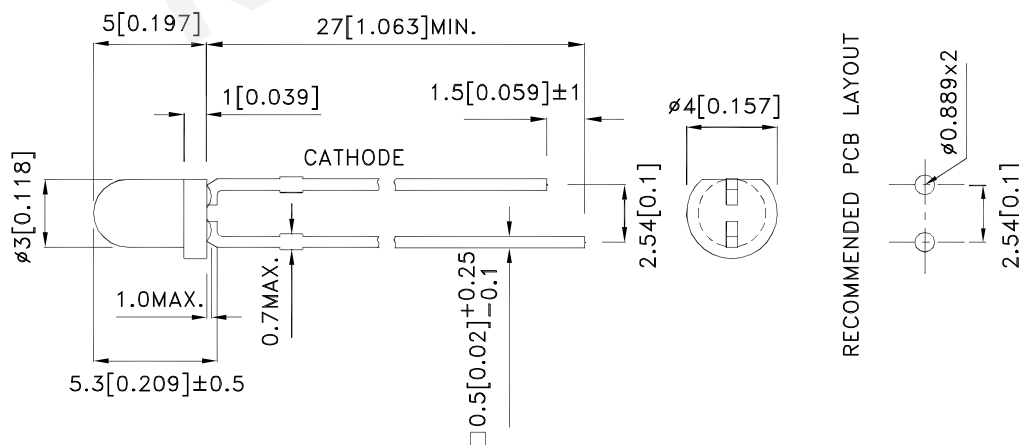
Features

- T-1 package with rectangular base.
- With built-in blinking IC.
- Operation voltage from 3.5V to 14V.
- Blinking frequency from 3.0Hz to 1.5Hz.
- RoHS compliant.

Descriptions

- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



Notes:

- Notes:
1. All dimensions are in millimeters (inches).
 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) V= 9V		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-36BGD	Green (GaP)	Green Diffused	12	25	60°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Min.	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green		565		nm	
λD	Dominant Wavelength	Green		568		nm	
Δλ1/2	Spectral Line Half-width	Green		30		nm	
IF	Forward Current	Green	8	22		mA	Min:VF=3.5V Typ:VF=5V
ISON	Supply Current	Green		8		mA	VF=3.5V
ISON	Supply Current	Green		44		mA	VF=14V
f	Blink Frequency	Green	1.5		3	Hz	VF=3.5V~14V

Note:

1. Wavelength value is traceable to the CIE127-2007 compliant national standards.
2. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	310	mW
Forward Voltage	14	V
Reverse Voltage	0.5	V
Operating Temperature	-40°C To +70°C	
Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [1]	260°C For 3 Seconds	
Lead Solder Temperature [2]	260°C For 5 Seconds	

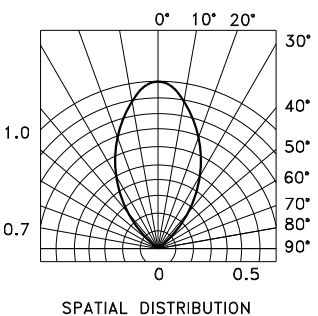
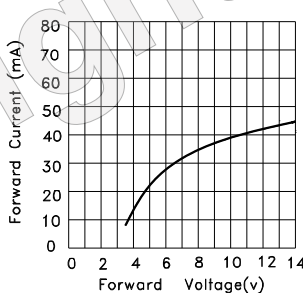
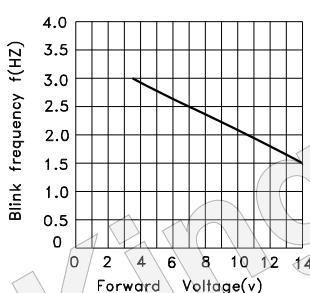
Notes:

1. 2mm below package base.
2. 5mm below package base.



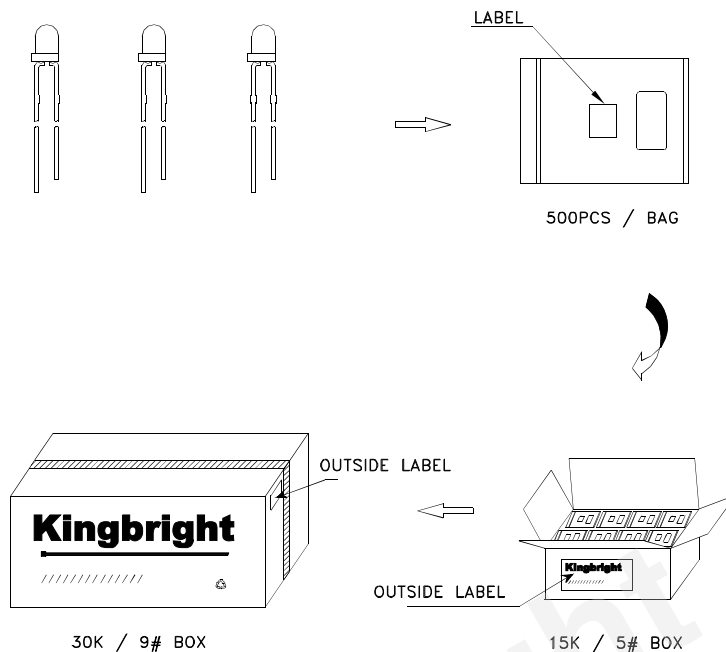
Green


L-36BGD



PACKING & LABEL SPECIFICATIONS

L-36BGD



Kingbright	
P/NO: L-36Bxxx	
QTY: 500 pcs	Q.C.
S/N: XXXX	Q C XX-XX-XXXX PASSED
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

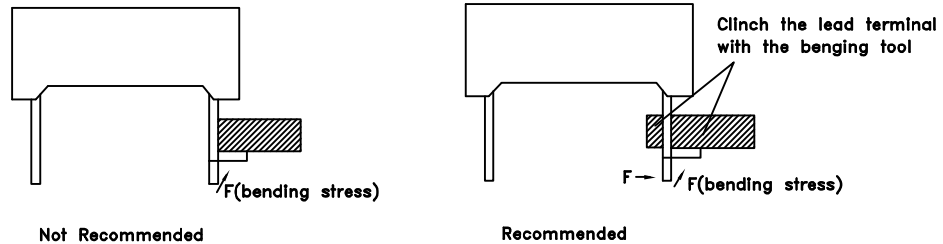
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THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

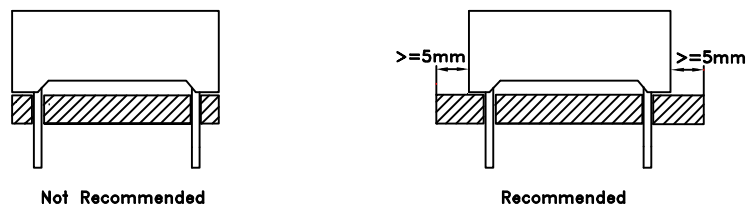


Installation

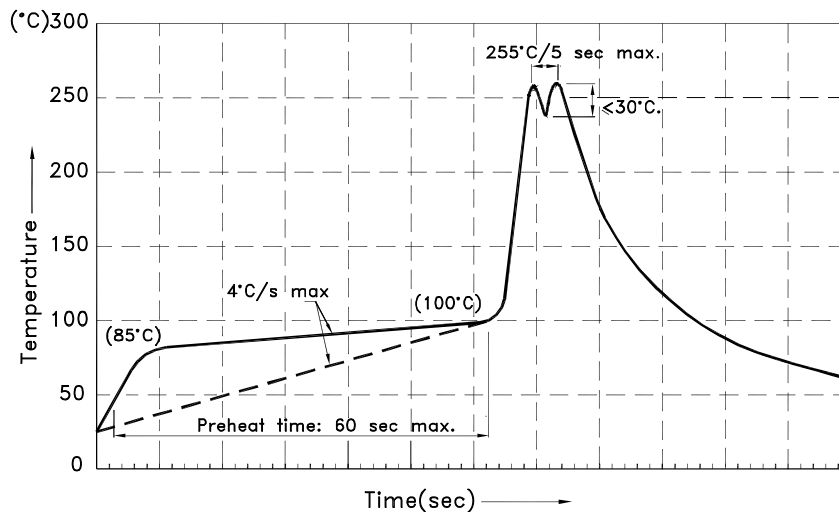
- 1.The installation process should not apply stress to the lead terminals.
- 2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



- 3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



Recommended Wave Soldering Profiles:



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.

